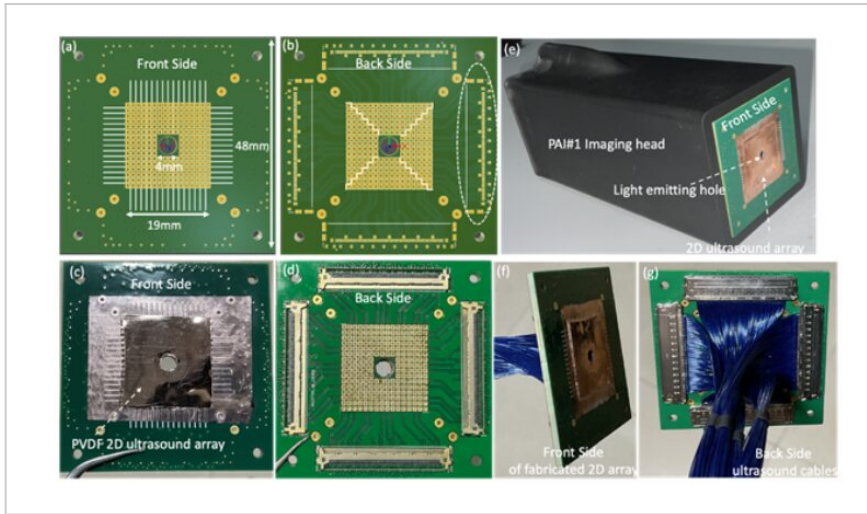


# Printed Circuit Board (PCB) Based Ultrasound Transducer Arrays for Multimodal Ultrasound and Photoacoustic Imaging

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TECHNOLOGY READINESS LEVEL

4



## Seeking

Licensing | Research

## Keywords

- Photoacoustic Imaging
- Ultrasound Transducer Fabrication
- 2D Matrix Transducer Array
- Printed Circuit Board (PCB)
- Polyvinylidene Fluoride (PVDF)
- Beamforming

## Researchers

**Dr. Sri-Rajasekhar Kothapalli**  
Associate Professor

## Haoyang Chen

Ph.D. Candidate

## Shubham Khandare

Ph.D. Candidate

## Mahaan Mitra

Ph.D. Candidate

## Other Researchers

## Originating College

College of Engineering

## Office of Technology Management Contact

Robert Prosak  
rbp5558@psu.edu

## Technology Summary

Photoacoustic (PA) imaging provides deep tissue molecular imaging of chromophores with optical absorption contrast and ultrasonic resolution. Present PA imaging techniques are predominantly limited to one 2D plane per acquisition. 2D ultrasound transducers, required for real-time 3D PA imaging, are high-cost, complex to fabricate and have limited scalability in design.

## Application & Market Utility

Researchers at The Pennsylvania State University have developed novel PCB-based 2D matrix ultrasound transducer arrays that are capable of being bulk manufactured at low-cost without using laborious ultrasound fabrication tools. The 2D ultrasound array specifications are easily scalable with respect to widely available PCB design and fabrication tools at low cost. To demonstrate scalability, they fabricated low (11 MHz) frequency 8x8 element and 16x16 element matrix arrays, in addition to a high (40 MHz) frequency 4x4 matrix array by directly bonding an undiced polyvinylidene fluoride (PVDF) piezoelectric material of desired thickness to the custom designed PCB substrate. Characterization results demonstrate wideband PA receive sensitivity for both low (87%) and high (188%) frequency arrays. Volumetric PA imaging results of light absorbing targets inside optical scattering medium demonstrate improved spatial resolution and field of view with increase in aperture size.

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## Next Steps

Seeking licensing opportunities and collaborators.